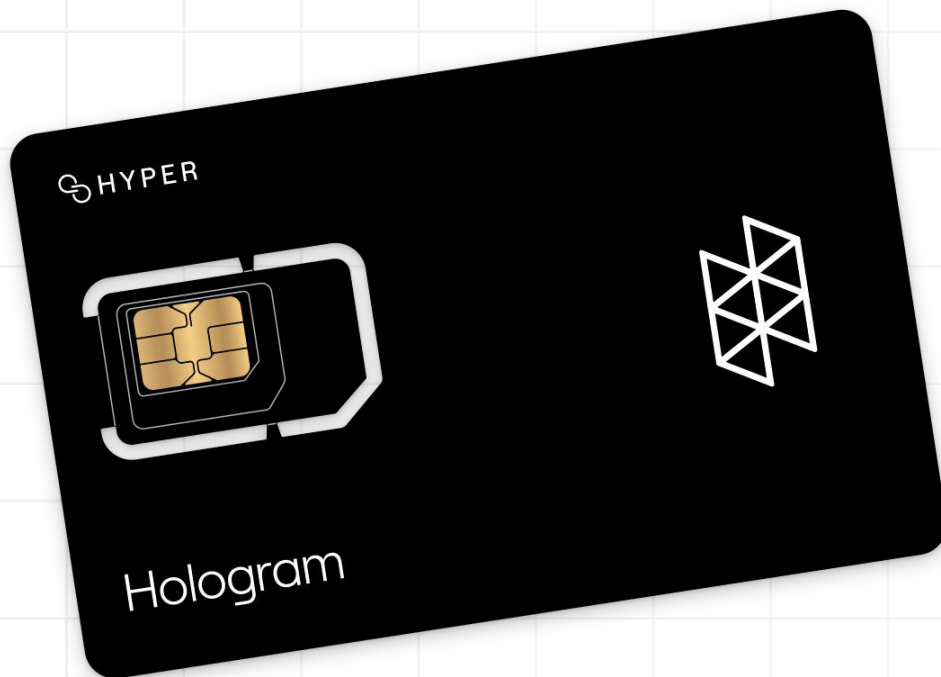


# Hyper eUICC SIM

Triple cut format



# Hyper eUICC SIM – Triple Cut Format

## Product overview

A secure, device-agnostic IoT SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIM platform is eUICC compliant and remotely updates coverage over-the-air by adding or removing connectivity profiles, without requiring you to swap the SIM in your device. Network fallback functionality can dynamically switch profiles in the event that a profile loses connectivity.

## Network availability

Works globally with Hologram's 2G through 5G network including LTE-M and NB-IoT where coverage is available. More information: <https://www.hologram.io/pricing/coverage>

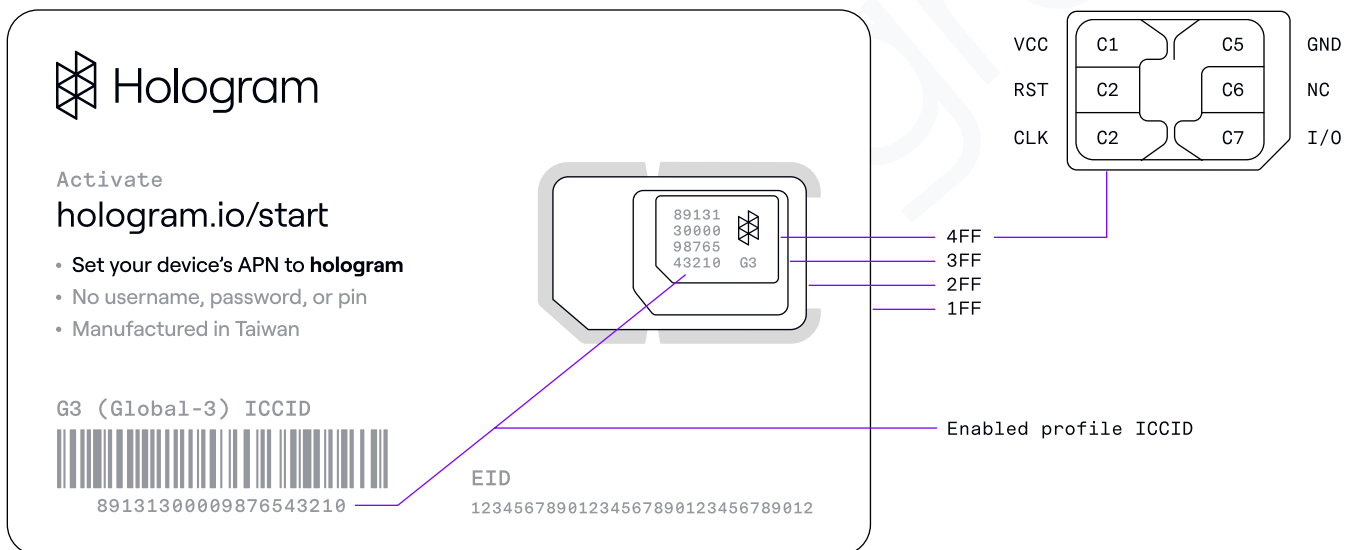
## Part numbers

G3-F  
G3

## Multipack labeling

Single SIM: G3-F  
10-pack: G3-F-10  
100-pack: G3-F-100  
1000-pack: G3-F-1000

## Mechanical specifications



## Physical characteristics

### Size

Size	Form Factor	Dimensions (mm)
1FF	Full-size	85.6 x 54 x 0.71 mm
2FF	Mini-SIM	25 x 15 x 0.71 mm
3FF	Micro-SIM	15 x 12 x 0.71 mm
4FF	Nano-SIM	12.3 x 8.8 x 0.71 mm

### Pin definitions

Pin	Signal	Description
C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

## Hardware features

### Chip type

Supplier	Infineon
Chip Code	SLM17ECB800B

### Electrical

Operating Voltage	1.62V to 5.5V
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### Hardware characteristics

Grade	Industrial
Operational Temperature	-40°C to +105°C
Data Retention	10 years @ 25°C
Write Endurance	>1.5M cycles
Memory (NVM)	800 KB
Memory (SRAM)	20 KB

### AC electrical parameters standards

ETSI 3GPP TS 102 221 v16.0.0 - Smart Cards; UICC-Terminal interface; Physical and logical characteristics  
ISO/IEC 7816, T=0 standard for Cards with contacts – USB electrical interface and operating procedures

## Compliance

Chip	 Common Criteria	EAL 4+ PP-0084 (chipset) Certificate: BSI-DSZ-CC-1126-V2-2021
OS		SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
	 TRUSTED CONNECTIVITY ALLIANCE	SIMalliance eUICC Profile Package Interoperable Format Technical Specification v2.3.1
		Card Specification Version 2.3.1 Card Specification Amendments A, B, D & E
Software		Java Card 3 Platform, Classic Edition version 3.0.5
		Release 16
Remote SIM provisioning		SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
Supplier's Declaration of Conformity		Manufactured according to the following standards: <ul style="list-style-type: none"> <li>• RoHS Directive 2011/65/EU</li> <li>• Reach certification</li> <li>• GSMA SAS-UP</li> <li>• ISO 9001:2015</li> <li>• ISO 27001</li> <li>• ISO 14001</li> </ul>